



## Material Content Data Sheet



<b>Sales Product Name</b>		SKB02N120		<b>Issued</b>		19. July 2018		
<b>MA#</b>		MA000598638						
<b>Package</b>		PG-TO263-3-2		<b>Weight*</b>		1558.71 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.571	0.22	0.22	2214	2214
leadframe	non noble metal	iron	7439-89-6	0.304	0.02		189	
	inorganic material	phosphorus	7723-14-0	0.091	0.01		57	
	non noble metal	copper	7440-50-8	304.026	18.84	18.87	188449	188695
wire	non noble metal	aluminium	7429-90-5	1.416	0.09	0.09	878	878
encapsulation	organic material	carbon black	1333-86-4	10.313	0.64		6393	
	plastics	epoxy resin	-	113.447	7.03		70319	
	inorganic material	silicondioxide	60676-86-0	563.796	34.95	42.62	349465	426177
leadfinish	non noble metal	tin	7440-31-5	9.657	0.60	0.60	5986	5986
plating	non noble metal	nickel	7440-02-0	0.228	0.01		142	
	inorganic material	phosphorus	7723-14-0	0.001	3.38	3.39	33844	33986
solder	noble metal	silver	7440-22-4	0.087	0.01		54	
	non noble metal	tin	7440-31-5	0.070	0.00		43	
	non noble metal	lead	7439-92-1	3.319	0.21	0.22	2057	2154
heatspreader	non noble metal	iron	7439-89-6	0.548	0.03		340	
	inorganic material	phosphorus	7723-14-0	0.165	0.01		102	
	non noble metal	copper	7440-50-8	547.666	33.95	33.99	339468	339910
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com